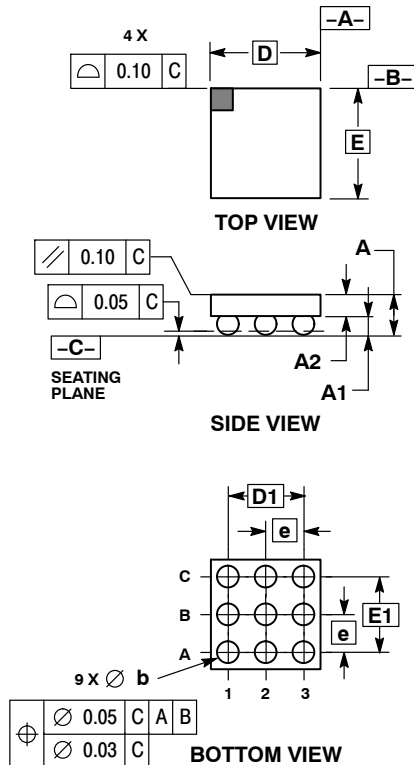


**9 PIN FLIP-CHIP**  
**CASE 499E**  
**ISSUE A**

DATE 30 JUN 2004



SCALE 4:1

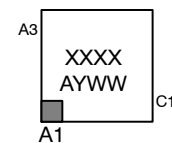


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

MILLIMETERS		
DIM	MIN	MAX
A	0.540	0.660
A1	0.210	0.270
A2	0.330	0.390
D	1.450 BSC	
E	1.450 BSC	
b	0.290	0.340
e	0.500 BSC	
D1	1.000 BSC	
E1	1.000 BSC	

**GENERIC**  
**MARKING DIAGRAM\***



XXXX = Specific Device Code  
 A = Assembly Location  
 Y = Year  
 WW = Work Week  
 G or ■ = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking.  
 Pb-Free indicator, "G" or microdot "■", may or may not be present.

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<b>DESCRIPTION:</b>	<b>9 PIN FLIP-CHIP, 1.45 X 1.45 MM</b>	<b>PAGE 1 OF 1</b>

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